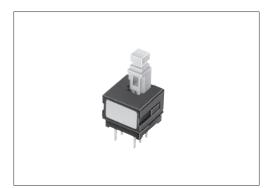
Vertical push switch with two types of knob available







Typical Specifications

Ite	ms	Specifications		
Rating (max.)/(mi (Resistive load)	n.)	0.1A 30V DC / 50μA 3V DC		
Contact resistance (Initial/After operation	-	20 m Ω max. $/$ 40 m Ω max.		
Operating force		Refer to the products line		
Operating life	Without load	10,000 cycles		
Operating me	With load	10,000 cycles (0.1A 30V DC)		

Product Line

Changeover	Travel	Total travel	Mounting	Poles	knob	Operating	Operation	Terminal	Minimum ord		Product No.	Drawing	
timing	(mm)	(mm)	method		style	force		type	Japan	Export		No.	
				_	Standard	_	Latching	- Straight			SPPH110800	1	
							Momentary				SPPH110300		
					Short		Latching				SPPH120400	- 2	
					SHOLL	2 + 1 2 - 0.7 N	Momentary				SPPH120100		
	1.5 2	2.5			Standard	dard	Latching				SPPH130400		
Non shorting			PC board					Momentary	Snap-in	800	4,000	SPPH130100	'
					Short		Latching	J Shap-in			SPPH140300	2	
						311011	OI IOI C	Momentary				SPPH140100	
					Standard	3 ⁺¹ _{-0.7} N		Straight			SPPH110900	1	
							Latching	Snap-in			SPPH130500		
								Short			Gridp-III		

Packing Specifications

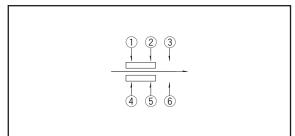
Number of pa	ckages (pcs.)	Export package measurements
1 case / Japan	1 case / export packing	(mm)
800	4,000	400×270×290

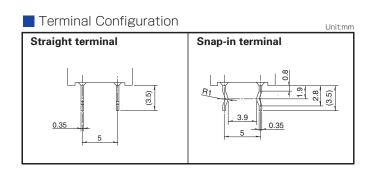


Unit:mm PC board mounting hole dimensions (Viewed from the direction A) No. Style Straight terminal Snap-in terminal Travel Total travel 1 ø0.9 hole ø0.9 hole Thickness of PC board t=1.6mm Terminal No.4 Straight terminal Snap-in terminal 10 Total travel 2 Terminal No.4 ø0.9 hole ø0.9 hole Thickness of PC board t=1.6mm

■ Circuit Diagram (Viewed from Direction A)

Dimensions





					Veri	tical		
Series		SPEH	SPEG	SPEJ	SPPH2	SPPH4	SPPH1	
Photo								
		W	6	7.19	7	6	6.5	10
Dimensio (mm)	ons	D	6	8.39	7	6.5	8.5	10
		Н	5	3.5	5.95	6.5 8.5		.5
Tra	vel (mm)	_	_	1.7	1	2.2	1.5
Total	travel (n	nm)	1.6	1.1	1.7	1.5	3	2.5
Numb	er of po	les	1	1	2		2	
	perating rature ra		-40℃ to +90℃	-10°C to +60°C	-40℃ to +85℃	−10°C to +60°C		
Auto	Automotive use		•	_	•	_	_	•
Li	fe cycle		*3	*3	*3	X X		*3
	ng (max istive loa		50mA 16V DC	1mA 5V DC	0.2A 14V DC	0.1A 12V DC 0.1A 30V DC		OV DC
	ing (min istive loa		10μA 1V DC	50μA 3V DC	_		50μA 3V DC	
Durability		nting life out load	100,000 cycles 400mΩ max.	$30,000$ cycles $500\text{m}\Omega$ max.	10,000 cycles 150mΩ max.	10,000 cycles 50mΩ max.	10,000 cycles 100mΩ max.	10,000 cycles 40mΩ max.
Durability		life with load rated load)	100,000 cycles 400mΩ max.	$30,000$ cycles $500\text{m}\Omega$ max.	10,000 cycles 150mΩ max.	10,000 cycles 50mΩ max.	10,000 cycles 100mΩ max.	10,000 cycles 40mΩ max.
		contact stance	200mΩ max.	200mΩ max.	150mΩ max.	30mΩ max.	100mΩ max.	20mΩ max.
Electrical performance	Insulation resistance		100MΩ min. 100V DC	3MΩ min. 100V DC	100MΩ min. 500V DC	100MΩ min. 500V DC		C
	Volta	ge proof	250V AC for 1minute	100V AC for 1minute	500V AC for 1minute	500V AC for 1minute		
	Terminal strength		_	0.5N for 1minute	_	5N for 1minute		
Mechanical performance	Actuato	Operating direction	50	N	49N	30	ON	50N
	strength	Pulling direction	_	_	_	_	10N	_
	Cold		-40°C 1,000h	-20℃ 96h	-40℃ 500h	-20°C 96h		
Environmental performance	Dry heat		90℃ 1,000h	85°C 96h	85°C 500h	85℃ 96h		
	Damp heat		60°C, 90 to 95% RH 1,000h	40°C, 90 to 95% RH 96h	60°C, 90 to 95% RH 500h	40°C,90 to 95%RH 96h		
	Page		126	127	128	129 131 132		

Note

Indicates applicability to all products in the series.



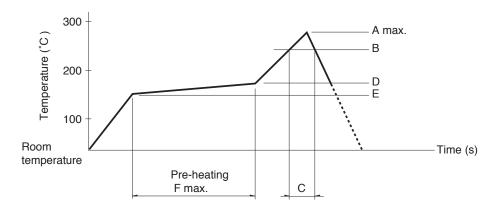
Push Switches Soldering Conditions

Example of Reflow Soldering Condition

1. Heating method: Double heating method with infrared heater.

2. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

3. Temperature profile



Series (Reflow type)	A (℃) 3s max.	B (℃)	C (s)	D (°C)	E (℃)	F (s)
SPEG						
SPEJ	260	230	40	180	150	120
SPEF	200					
SPEH						

Notes

- 1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc.

 The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Series	Soldering temperature	Soldering time	
SPPJ3, SPPJ2, SPUN, SPPH4, SPPH1	350±10℃	3+1/0s	
SPED2, SPED4	350±10℃	3±0.5s	
SPEJ	350±10°C	4s max.	
SPEG, SPEF	350±5℃	3s max.	
SPEH, SPPH2	350°C max.	3s max.	
SPUJ	300±10℃	3+1/0s	

Reference for Dip Soldering (For PC board terminal types)

Series	Ite	ms	Dip soldering		
Jenes	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion	
SPPJ3	100°C max. 60s max.		260±5℃	5±1s	
SPUN	100℃ max. 60s max.		260±5℃	10±1s	
SPUJ, SPPH2, SPPH4	_		260±5℃	5±1s	
SPPJ2, SPPH1, SPED2, SPED4, SPEF	_		260±5℃	10±1s	

